

# UVTOP305-FW-TO39

- Deep Ultraviolet Light Emission Source
- 310 nm, 1.0 mW
- TO39 Package
- Flat sapphire window
- Biological and Chemical Analysis





## Description

**UVTOP305-FW-TO39** is a deep ultraviolet light emission source, based on **AIGAN** quantum structures, typically emitting at **310 nm** with an optical output power of **1.0 mW**. It comes in hermetically sealed TO39 metal can package with a flat sapphire window, is Lead-free, and RoHS compliant. **UVTOP305-FW-TO39** is widely used for biological and chemical analysis, disinfection, optical sensing, and fluorescent spectroscopy applications.

## Maximum Rating (TCASE = 25°C)

Parameter	Symbol	Val	Herit	
		Min.	Max.	Unit
Power Dissipation, DC	PD		180	mW
Forward Current*	<i>I</i> F		30	mA
Operating Temperature*	$T_{OPR}$	- 30	+ 55	°C
Storage Temperature	$T_{STG}$	- 30	+ 100	°C
Soldering Temperature	$T_{SOL}$		+ 190	°C

<sup>\*</sup> Operation close to the absolute maximum ratings may affect device reliability

## Electro-Optical Characteristics (TCASE = 25°C, IF = 20 mA)

Parameter	Symbol	Values			Unit
		Min.	Тур.	Max.	Onit
Peak Wavelength*1	$\lambda_{P}$	305		315	nm
Spectral Width (FWHM)	$\Delta \lambda$		11	15	nm
Forward Voltage*2	VF		6.0	7.5	V
Radiated Power*3	PO	0.4	1.0		mW
Beam Angle	201/2		120		deg.
Thermal Resistance	R <sub>th</sub>		50		°C/W

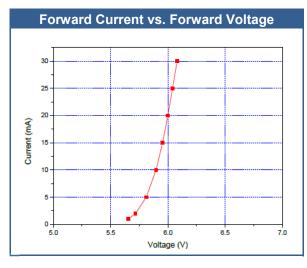
<sup>\*1</sup>wavelength measurement tolerance: ± 3 nm

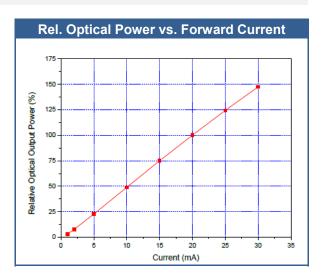
 $<sup>^{\</sup>star3} \text{output}$  power measurement tolerance: ± 10 %

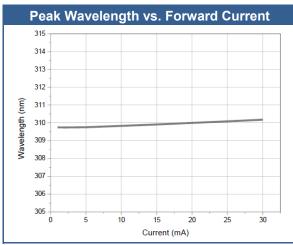


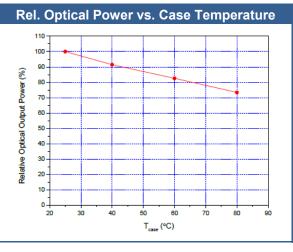
<sup>\*2</sup>forward voltage measurement tolerance: ± 3 %

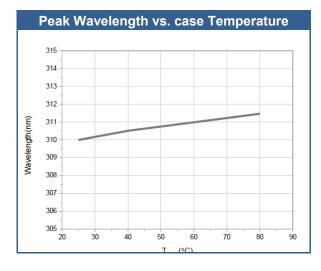
## **Performance Characteristics**

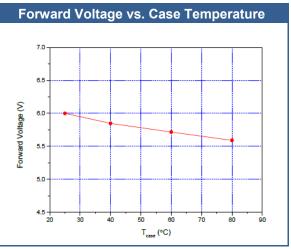






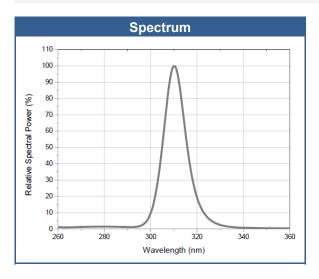


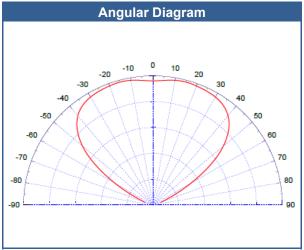






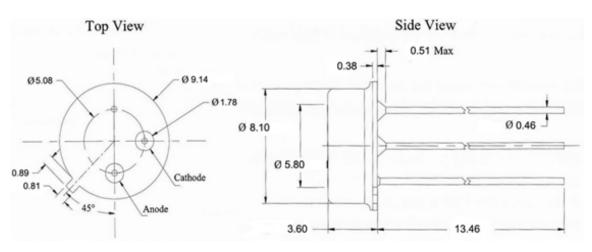
## **Performance Characteristics**





# **Outline Dimensions**

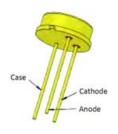
#### TO-39 flat window



All dimensions in mm

## **Electrical Connection**

Pin#	Function
Pin 1	Anode
Pin 2	Cathode
Pin 3	Case







### **Precautions**

#### Soldering:

- · Do avoid overheating of the LED
- Do avoid electrostatic discharge (ESD)
- Do avoid mechanical stress, shock, and vibration
- Do only use non-corrosive flux.
- Do only solder the leads. Soldering of header or cap will damage the LED
- Do only cut the leads at room temperature with an ESD protected tool
- Do not solder closer than 3 mm from base of the header
- Do form leads prior to soldering
- Do not impose mechanical stress on the header when forming the leads
- Do not apply current to the LED until it has cooled down to room temperature after soldering

#### Recommended soldering conditions:

dip soldering		hand soldering		
pre-heat time	max 30 s	soldering time	max 5 s	
dipping time	max 5 s			
solder bath temperature	max 190 °C	solder temperature	max 190 °C	

It is strongly advised to perform soldering at the shortest time and lowest temperature possible.

#### Cleaning:

Cleaning with isopropyl alcohol, propanol, or ethyl alcohol is recommended

DO NOT USE acetone, chloroseen, trichloroethylene, or MKS

DO NOT USE ultrasonic cleaners

#### **Static Electricity:**

**UVTOP** are sensitive to electrostatic discharge (ESD). Precautions against ESD must be taken when handling or operating these LEDs. Surge voltage or electrostatic discharge can result in complete failure of the device.

#### **UV-Radiation:**

During operation these LEDs do emit **high intensity ultraviolet light**, which is hazardous to skin and eyes, and may cause cancer. Do avoid exposure to the emitted UV light. **Protective glasses are recommended**. It is further advised to attach a warning label on products/systems that do utilize UV-LEDs:





# WARNING

#### UV I FDs

High intensity ultraviolet light
Eye and skin hazard - avoid exposure to eyes/skin
Do not look directly at light - use eye protection
Use warning labels on systems containing UV LEDs

#### Operation:

#### Do only operate UVTOP LEDs with a current source.

Running these LEDs from a voltage source will result in complete failure of the device.

Current of a LED is an exponential function of the voltage across it. Usage of current regulated drive circuits is mandatory



## **Device Materials**

Pin #	Material
Header	Fe-Ni alloy, plated Ni-Au
Leads	Fe-Ni alloy, plated Ni-Au
Bonding wires	Au
Lens	SiO <sub>2</sub>



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